

Amendments to the Specification

Please enter the following amendments to the specification:

Please replace paragraph [0004] at page 1 of the specification with the following new paragraph [0004]:

[0004] Undoped silica glass (SiO_2), subsequently referred to herein as "USG", has been long used in integrated circuits as a primary ~~insulating~~ insulating material because of its relatively lower dielectric constant of approximately 4.0 compared to other inorganic materials. The industry has attempted to produce silica-based materials with lower dielectric constants by incorporating organics or other materials within the silicate lattice. For example, dielectric constants ranging from 2.7 to 3.5 can be achieved by incorporating terminal groups such as fluorine or methyl into the silicate lattice. These materials are typically deposited as dense films (density $\sim 1.5 \text{ g/cm}^3$) and integrated within the IC device using process steps similar to those for forming USG films.

Please replace paragraph [0078] at page 22 of the specification with the following new paragraph [0078]:

[0078] In certain preferred embodiments, the one or more energy sources comprise an ultraviolet light source. The temperature that the substrate is subjected to during exposure to an ultraviolet light source typically ranges from between 200 to 400°C. The composite film may be exposed to one or more wavelengths within the ultraviolet spectrum or one or more wavelengths within the ultraviolet spectrum such as deep ultraviolet light (i.e., wavelengths of 280 nm or below) or vacuum ultraviolet light (i.e., wavelengths of 200 nm or below). The ultraviolet light may be dispersive, focused, continuous wave, pulsed, or shuttered. Sources for the ultraviolet light include, but are not limited to, an excimer laser, a barrier discharge lamp, a mercury lamp, a microwave-generated UV lamp, a laser such as a frequency doubled or frequency tripled laser in the IR or visible region, or a two-photon absorption from

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a laser in the visible region, or a picosecond or sub-picosecond laser. The ultraviolet light source may be placed at a distance that ranges from 50 milli-inches to 1,000 feet from the composite film.